CLAIMS

1. A method of assembling a packaged electronic module for use with a smart card, the method comprising the steps:

(A) providing a first contact plate including a first electrical connector, the first electrical connector being configured with a first surface of the first contact plate;

(B) providing a first printed circuit including a second electrical connector, the second electrical connector being configured with a first surface of the first printed circuit;

(C) joining the contact plate and the printed circuit such that the first electrical connector and the second electrical connector are electrically mated to form a packaged electronic module;

wherein the first printed circuit includes one or more electronic components, and the second electrical connector of the first printed circuit is electrically connected to at least one of the one or more electronic components;

wherein the electrical mating of the first electrical connector with the second electrical connector in (C) forms a gap between the first surface of the first contact plate and the first surface of the first printed circuit, and wherein at least one of the one or more electronic components fits within the gap.

2. The method of claim 1 wherein the first surface (104) of the first contact plate (100) includes the bottom (104) of the first contact plate and the first surface of the first printed circuit includes the top of the first printed circuit.

3. The method of claim 1 wherein the first contact plate includes one or more contact points, and the first electrical connector of the first contact plate is electrically connected to at least one of the one or more contact points.

4. The method of claim 1 wherein the first printed circuit includes one or more value add components selected from the group: a display, a fingerprint sensor, and an LED device.

5. The method of claim 1 wherein the first contact plate and/or the first printed circuit is configured with an antenna.

6. The method of claim 1 wherein the first contact plate is included in a first contact plate tape.

7. The method of claim 1 wherein the first printed circuit is included in a first printed circuit tape.

8. A method of assembling packaged electronic modules according to anyone of claims 1 to 7, comprising: combining a tape comprising a plurality of contact plates with a tape comprising a plurality of printed circuits to form a combined tape of corresponding pluralities of packaged electronic modules.